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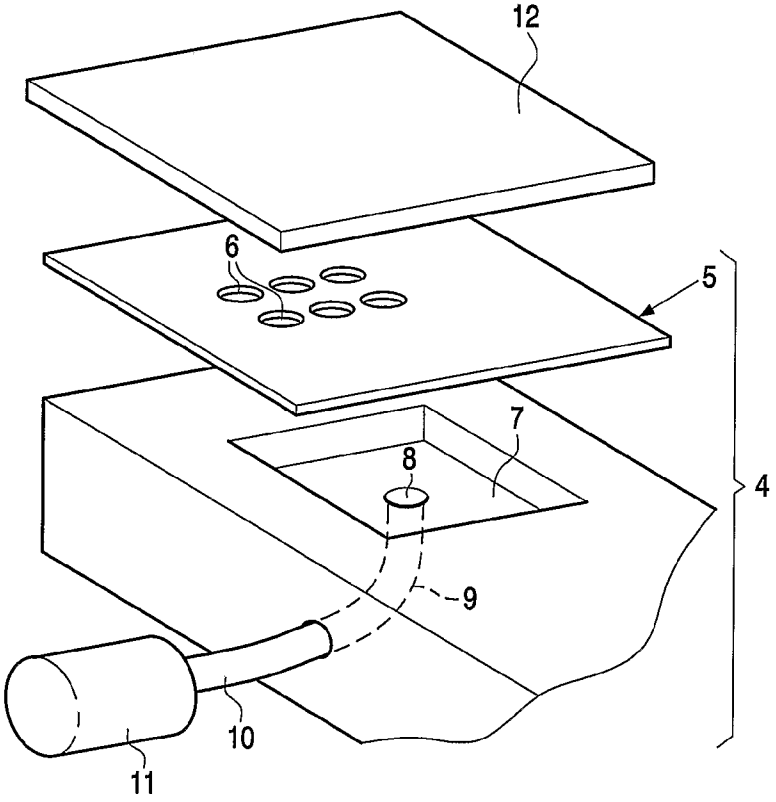
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(54) Title: CARRIER, HOLDER, LASER CUTTING DEVICE AND METHOD FOR SEPARATING SEMICONDUCTOR PRODUCTS USING LASER LIGHT



(57) Abstract: The invention relates to a carrier and to a holder for supporting and engaging semiconductor products during separating of the products using laser light. The invention also relates to a method for supporting and engaging semiconductor products during separating of the products using laser light.

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